

**AP4955M**

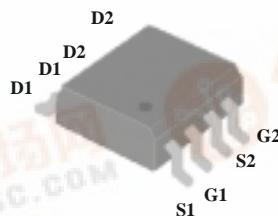
**Advanced Power  
Electronics Corp.**

**P-CHANNEL ENHANCEMENT MODE  
POWER MOSFET**

▼ Simple Drive Requirement

▼ Low Gate Charge

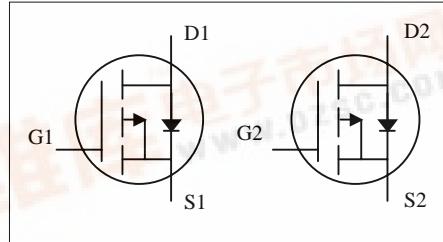
▼ Fast Switching Characteristic



$BV_{DSS}$	-20V
$R_{DS(ON)}$	45mΩ
$I_D$	-5.6A

## Description

The Advanced Power MOSFETs from APEC provide the designer with the best combination of fast switching, ruggedized device design, lower on-resistance and cost-effectiveness.



## Absolute Maximum Ratings

Symbol	Parameter	Rating	Units
$V_{DS}$	Drain-Source Voltage	-20	V
$V_{GS}$	Gate-Source Voltage	$\pm 20$	V
$I_D @ T_A = 25^\circ C$	Continuous Drain Current <sup>3</sup>	-5.6	A
$I_D @ T_A = 70^\circ C$	Continuous Drain Current <sup>3</sup>	-4.5	A
$I_{DM}$	Pulsed Drain Current <sup>1</sup>	20	A
$P_D @ T_A = 25^\circ C$	Total Power Dissipation	2	W
	Linear Derating Factor	0.016	W/°C
$T_{STG}$	Storage Temperature Range	-55 to 150	°C
$T_J$	Operating Junction Temperature Range	-55 to 150	°C

## Thermal Data

Symbol	Parameter	Value	Unit
$R_{thj-a}$	Thermal Resistance Junction-ambient <sup>3</sup>	Max.	°C/W



## Electrical Characteristics@ $T_j=25^\circ\text{C}$ (unless otherwise specified)

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
$\text{BV}_{\text{DSS}}$	Drain-Source Breakdown Voltage	$V_{\text{GS}}=0\text{V}$ , $I_{\text{D}}=-250\mu\text{A}$	-20	-	-	V
$\Delta \text{BV}_{\text{DSS}}/\Delta T_j$	Breakdown Voltage Temperature Coefficient	Reference to $25^\circ\text{C}$ , $I_{\text{D}}=-1\text{mA}$	-	-0.01	-	$\text{V}/^\circ\text{C}$
$R_{\text{DS}(\text{ON})}$	Static Drain-Source On-Resistance <sup>2</sup>	$V_{\text{GS}}=-4.5\text{V}$ , $I_{\text{D}}=-5\text{A}$	-	-	45	$\text{m}\Omega$
		$V_{\text{GS}}=-2.5\text{V}$ , $I_{\text{D}}=-4\text{A}$	-	-	65	$\text{m}\Omega$
$V_{\text{GS}(\text{th})}$	Gate Threshold Voltage	$V_{\text{DS}}=V_{\text{GS}}$ , $I_{\text{D}}=-250\mu\text{A}$	-0.5	-	-1.2	V
$g_{\text{fs}}$	Forward Transconductance	$V_{\text{DS}}=-5\text{V}$ , $I_{\text{D}}=-5\text{A}$	-	9	-	S
$I_{\text{DSS}}$	Drain-Source Leakage Current ( $T_j=25^\circ\text{C}$ )	$V_{\text{DS}}=-20\text{V}$ , $V_{\text{GS}}=0\text{V}$	-	-	-1	$\text{uA}$
	Drain-Source Leakage Current ( $T_j=70^\circ\text{C}$ )	$V_{\text{DS}}=-16\text{V}$ , $V_{\text{GS}}=0\text{V}$	-	-	-25	$\text{uA}$
$I_{\text{GSS}}$	Gate-Source Leakage	$V_{\text{GS}}=\pm 20\text{V}$	-	-	$\pm 100$	nA
$Q_g$	Total Gate Charge <sup>2</sup>	$I_{\text{D}}=-5\text{A}$	-	19	30	nC
$Q_{\text{gs}}$	Gate-Source Charge	$V_{\text{DS}}=-16\text{V}$	-	3	-	nC
$Q_{\text{gd}}$	Gate-Drain ("Miller") Charge	$V_{\text{GS}}=-4.5\text{V}$	-	6	-	nC
$t_{\text{d}(\text{on})}$	Turn-on Delay Time <sup>2</sup>	$V_{\text{DS}}=-10\text{V}$	-	9	-	ns
$t_r$	Rise Time	$I_{\text{D}}=-1\text{A}$	-	10	-	ns
$t_{\text{d}(\text{off})}$	Turn-off Delay Time	$R_G=3.3\Omega$ , $V_{\text{GS}}=-10\text{V}$	-	52	-	ns
$t_f$	Fall Time	$R_D=10\Omega$	-	24	-	ns
$C_{\text{iss}}$	Input Capacitance	$V_{\text{GS}}=0\text{V}$	-	1400	2240	pF
$C_{\text{oss}}$	Output Capacitance	$V_{\text{DS}}=-20\text{V}$	-	270	-	pF
$C_{\text{rss}}$	Reverse Transfer Capacitance	f=1.0MHz	-	230	-	pF

## Source-Drain Diode

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
$V_{\text{SD}}$	Forward On Voltage <sup>2</sup>	$I_{\text{S}}=-1.6\text{A}$ , $V_{\text{GS}}=0\text{V}$	-	-	-1.2	V
$t_{\text{rr}}$	Reverse Recovery Time <sup>2</sup>	$I_{\text{S}}=-5\text{A}$ , $V_{\text{GS}}=0\text{V}$ ,	-	32	-	ns
$Q_{\text{rr}}$	Reverse Recovery Charge	dl/dt=100A/ $\mu\text{s}$	-	22	-	nC

## Notes:

- 1.Pulse width limited by Max. junction temperature.
- 2.Pulse width  $\leq 300\mu\text{s}$  , duty cycle  $\leq 2\%$ .
- 3.Surface mounted on 1 in<sup>2</sup> copper pad of FR4 board ;  $135\text{ }^\circ\text{C}/\text{W}$  when mounted on min. copper pad.



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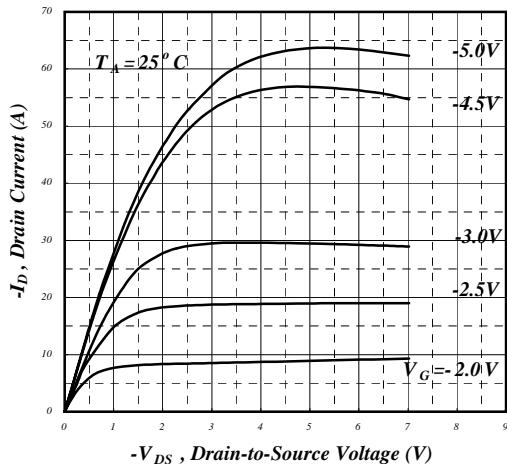


Fig 1. Typical Output Characteristics

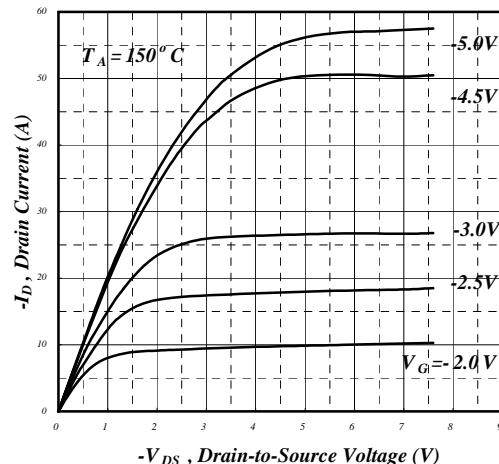


Fig 2. Typical Output Characteristics

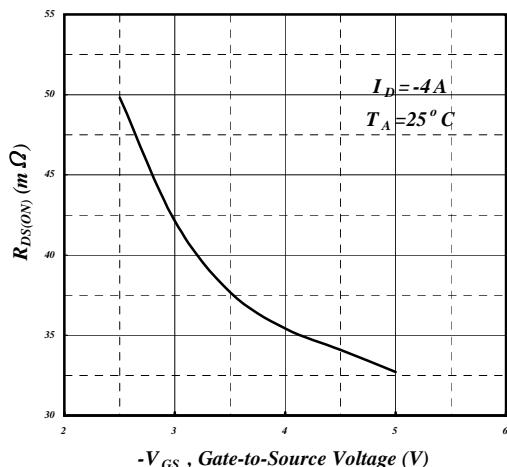


Fig 3. On-Resistance v.s. Gate Voltage

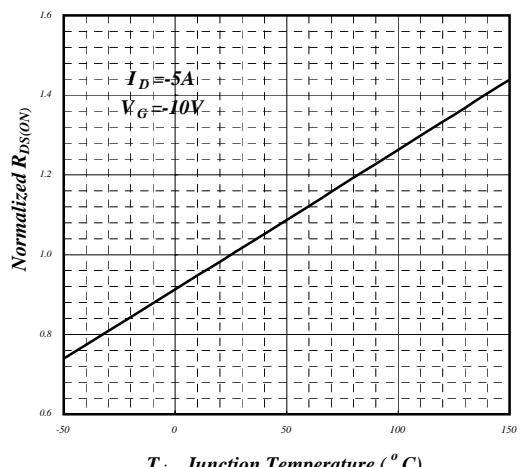


Fig 4. Normalized On-Resistance v.s. Junction Temperature

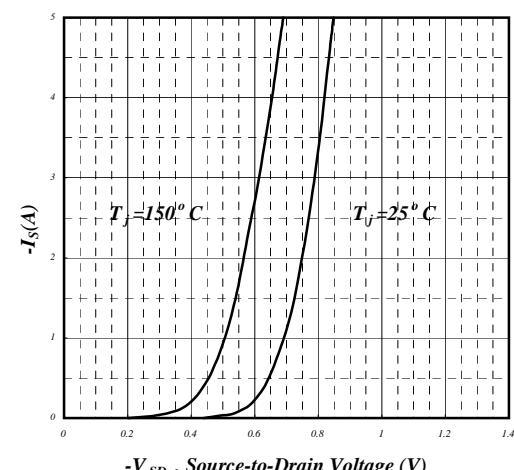


Fig 5. Forward Characteristic of Reverse Diode

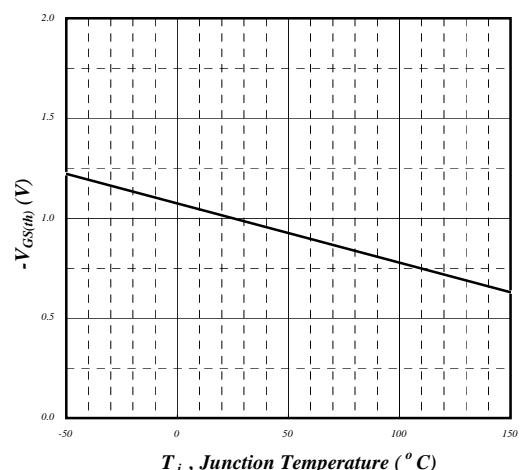
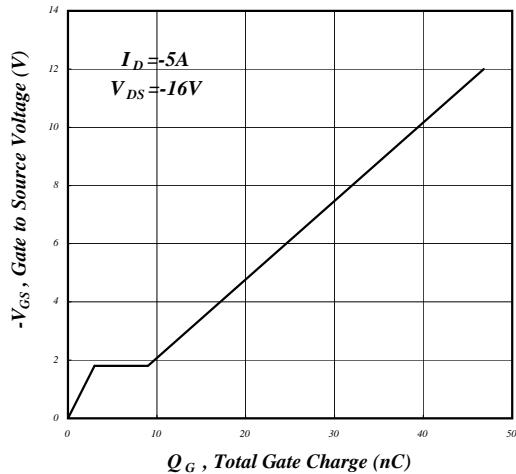


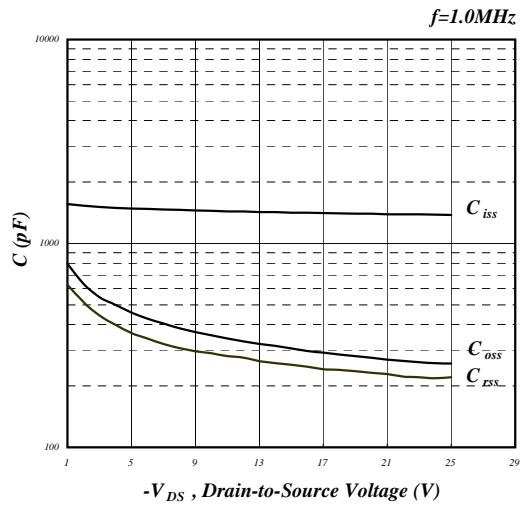
Fig 6. Gate Threshold Voltage v.s. Junction Temperature



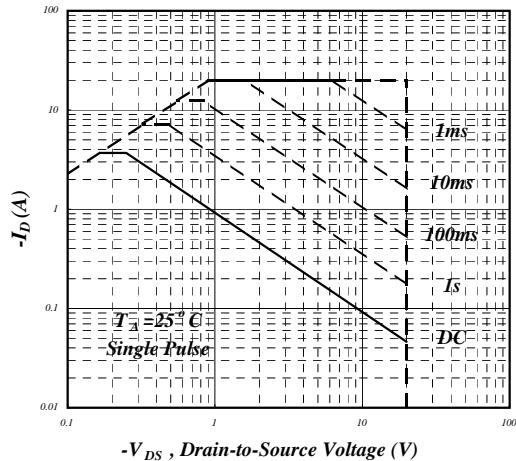
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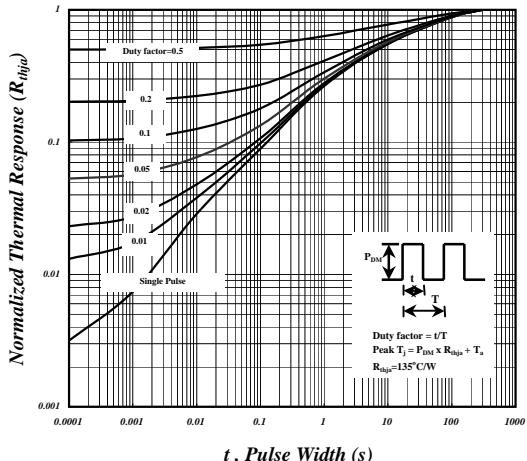
**Fig 7. Gate Charge Characteristics**



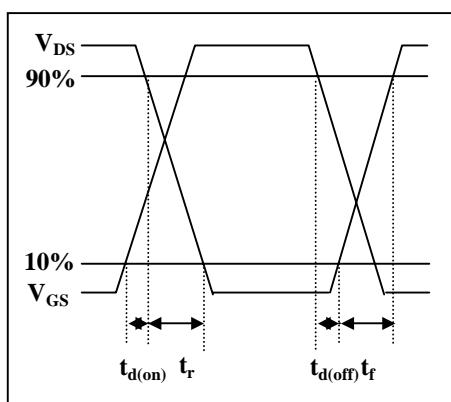
**Fig 8. Typical Capacitance Characteristics**



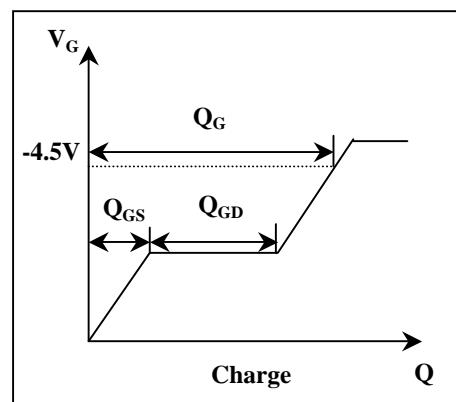
**Fig 9. Maximum Safe Operating Area**



**Fig 10. Effective Transient Thermal Impedance**



**Fig 11. Switching Time Waveform**



**Fig 12. Gate Charge Waveform**